

Cardinal Circuit

SEHO MWM 3250 Selective Solder

See Information Below:

The MWM 3250 is a modular selective SOLDERING system which may be totally tailored to meet your production requirements. At a later date it may even be upgraded to suit subsequent production developments.

The MWM 3250 is suitable to meet all requirements: productions with a high mix of assemblies typically use the miniwave SOLDERING process. High volume productions with only low board mix prefer a dip SOLDERING process with product specific multi nozzle tools to shorten cycle times.

If frequently changing products are manufactured in high production volumes, the MWM 3250 may be equipped with various SOLDERING units to cover different SOLDERING processes with only one machine system. Also conventional wave SOLDERING processes may be performed this way.

With its positioning accuracy of 0.05 mm, the robot – which guides the gripper - offers a maximum precision. Depending upon requirement different grippers for the processing of carriers or PCBs directly may be used.

The state-of-the-art solder nozzle technology effects the highest degree of precision. The solder nozzles perform a defined flow direction. These non-wettable, of course lead-free capable solder nozzles therefore show a reproducible flow behaviour and thus guarantee consistently good SOLDERING results. With minimum maintenance requirements, these SOLDERING nozzles are featured with a very high lifetime.

- High precision SCARA robot
- Maximum flexibility with different working stations which may be arranged in the process area according to your requirements
 - Short product change-over times
 - Gripper with directional functions for non-planar PCBs

- State-of-the-art solder nozzle technology
- Permanent wave height control
- Easy and quick online programming
- Comfortable offline teach program for maximum machine availability

Other Notes : SELECTIVE SOLDER, FLUXER, PRE-HEAT OVEN INCLUDED IN PACKAGE, WITH SPARE PARTS AND MANUALS.